		RECIPIENT
SPEC	IFICATIONS	
PRODUCT No.:	X1A000091000	100
MODEL:	FC-13A	
SPEC. No.:	Q17-028-1B	<u> </u>
DATE:	Jun. 26. 2017	<u> </u>
SEIKO EPS	SON CORPORATIO	ON
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PREPARED 7. Kurus	nigawo / TD·CS Quality	Assurance Department Senior Staff

Takashi kurumizawa

SPECIFICATIONS

1. Application

- 1) This document is applicable to the crystal unit that are delivered to Foryou Group Co.,Ltd from Seiko Epson Corp.
- 2) This product complies with RoHS Directive.
- 3) This Product supplied (and any technical information furnished, if any) by Seiko Epson Corporation shall not be used for the development and manufacture of weapon of mass destruction or for other military purposes. Making available such products and technology to any third party who may use such products or technologies for the said purposes are also prohibited.
- 4) This product listed here is designed as components or parts for electronics equipment in general consumer use. We do not expect that any of these products would be incorporated or otherwise used as a component or part for the equipment, which requires an systems, and medical equipment, the functional purpose of which is to keep extra high reliability, such as satellite, rocket and other space life.

This FC-13A is authorized for use of navigation system for automobile only.

2. Product No. / Model

The product No. of this crystal unit is X1A000091000100.

The model is FC-13A.

3. Packing

It is subject to the packing standard of Seiko Epson Corp.

4. Warranty

Defective parts which originate with us are replaced free of charge in the case of defects being found with 12 months after delivery.

5. Amendment and/or termination

Amendment and/or termination of this specification is subject to the agreement between the two parties.

6. Contents

Item No.	Item	Page
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[1] Absolute maximum ratings

			Rating value				
No	. Item	Symbol	Min.	Тур.	Max.	Unit	Note
1	Storage temperature range	T_stg	- 55		+ 125	°C	Suppose to be within CI STD at + 25 °C ± 3 °C.
2	Maximum level of drive	GL		0.5		μW	

[2] Operating range

			Rating value				
No.	Item	Symbol	Min.	Тур.	Max.	Unit	Note
1	Operating temperature range	T_use	- 40		+ 125	°C	
2	Level of drive	DL	0.01	0.1	0.5	μW	
3	Vibration mode		Fundamental				

[3] Static characteristics

No.	Item		Symbol	Value	Unit	Conditions
1	Nominal Frequency	7	f_nom	32.768	kHz	
2	Frequency tolerance		f_tol	± 20	× 10 ⁻⁶	CL = 12.5 pF Ta = $+25 \pm 3$ °C Level of drive : 0.1 μ W Not include aging
3	Motional resistance		R1	70 Max.	kΩ	
4	Motional capacitance		C1	3.2 Typ.	fF	CI meter : HP4294A Level of drive : 0.5 µW
5	Shunt capacitance		C0	0.9 Typ.	pF	
6	Frequency temperature	Turnover temperature	Ti	+ 25 ± 5	°C	Values are calculated by The frequencies
0	characteristics	Parabolic		- 0.04 Max.	× 10 ⁻⁶ /°C ²	at + 10, + 25, + 40 °C with C-MOS circuit.
7	Isolation resistance		IR	500 Min.	ΜΩ	DC 100V± 15, 60 seconds Between terminal # 1 and terminal # 2
8	Frequency Aging		f_age	± 3	× 10 ⁻⁶ /year	Ta = + 25 °C ± 3 °C Level of drive : 0.1 μW

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[4] Environmental and Mechanical characteristics

No.	Items	Value*1*2	Conditions
110.	Items	$\Delta f/f [1 \times 10^{-6}]$	
1	Shock resistance	*3 ± 10	Free drop from 1 000 mm height on a hard wooden board for 3 times
1	Shock resistance	3 ±10	(Board is thickness more than 30 mm)
			10 Hz to 55 Hz amplitude 0.75 mm
	Vibration resistance	*3 ± 5	55 Hz to 500 Hz acceleration 98 m/s ²
2	vibration resistance	*3 ± 5	$10 \text{ Hz} \rightarrow 500 \text{ Hz} \rightarrow 10 \text{ Hz} 15 \text{ min./cycle}$
			6 h (2 hours, 3 directions)
3	Soldering heat resistance	± 5	For convention reflow soldering furnace (3 times)
4	High temperature storage	*3 ± 20	+ 125 °C × 1 000 h
5	Low temperature storage	*3 ± 10	- 55 °C × 1 000 h
6	High temperature and	*3 ± 10	+ 85°C × 85%RH × 1 000 h
	humidity		
7	High Temperature bias	*3 ± 20	+ 125 °C × 1 000 h (Bias , Drive level ; 0.5 μ W)
8	Low Temperature bias	*3 ± 15	- 40 °C × 1 000 h (Bias , Drive level ; 0.5 μ W)
9	Temperature humidity storage bias	*3 ± 15	+ 85°C × 85 %RH × 1 000 h (Bias , Drive level ; 0.5 μ W)
10	Temperature cycle	*3 ± 15	- 40 °C ↔ + 125 °C
10	Temperature cycle	.3 113	30 minutes at each temperature × 1 000 cycles
11	Sealing	*3 1 × 10 ⁻⁸ hPa•1 / s Max.	For He leak detector
12	Shear	No peeling-off at a	20 N press for 10 ± 1 s.
12	Sileai	soldered part	Ref. IEC 60068-2-21
13	Pull - off	No peeling-off at a	20 N press for 10 ± 1 s.
13	ruii - OII	soldered part	Ref. IEC 60068-2-21
1.4	Substrata handing	No peeling-off at a	Bend width reaches 4 mm and hold for 20 s \pm 1 s \times 1 time
14	Substrate bending	soldered part	Ref. IEC 60068-2-21
		More than 95 %	Dip into methyl alcohol solution of rosin for 5 sec.
15	Solderability	covered by solder	at $+235 \pm 5$ °C

< Notes >

Shift of series resistance at before and after the test should be less than \pm 30 k Ω .

^{*1} Each test done independently.

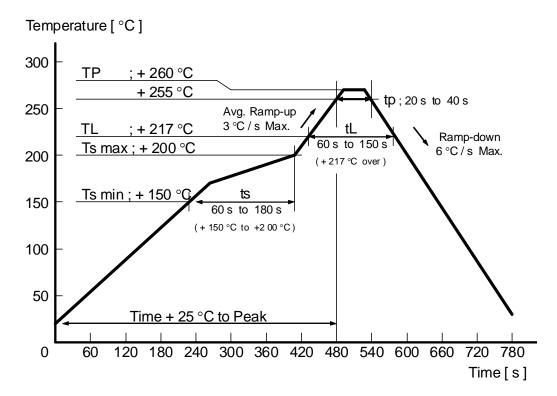
^{*2} Measuring 2 h to 24 h later leaving in room temperature after each test. Drive level : 0.5 μW

^{*3} Pre conditionings

^{1. + 125 °}C × 24 h \rightarrow +85 °C × 85 %RH × 168 h \pm 1 h \rightarrow reflow 3 times

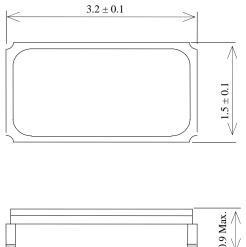
^{2.} Initial value shall be after 24 h at room temperature.

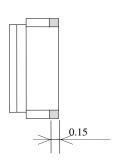
♦ Reflow condition (follow to IPC / JEDEC J-STD-020C)



4

[5] Dimensions and Internal Connection Dimension (Unit:mm)

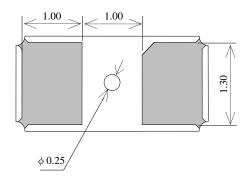


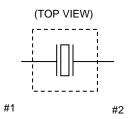




Internal Connection

(**) Lid does not connect with # 1 and # 2





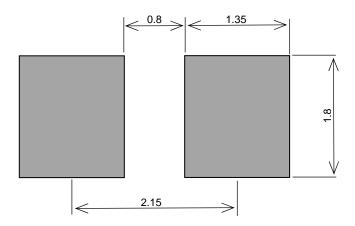
Terminal : Au plating

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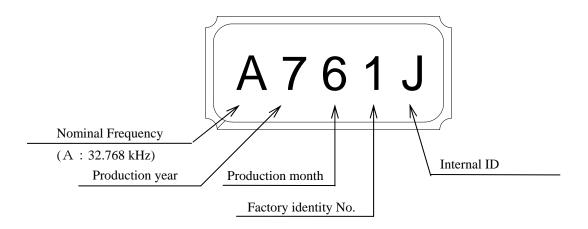
5

[6] Recommended soldering pattern and Marking layout

Recommended soldering pattern (Unit: mm)



Marking layout



Symbol of Manufacturing month

Byllicol of it	Iumuu	21411112	, momen	1								
Month digit	1	2	3	4	5	6	7	8	9	10	11	12
Marking	1	2	3	4	5	6	7	8	9	X	Y	Z

6

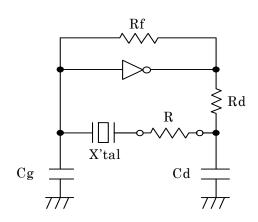
* The above marking layout shows only marking contents and their approximate position and it is not for font, size and exact position.

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[7] Notes

- 1. Max three (3) times reflow is allowed. Once miss soldering is happened, hand work soldering by soldering iron is recommended. (+350 °C × within 5 s)
- 2. Patterning should be followed by our recommended one.
- 3. Applying excessive excitation force to the crystal resonator may cause deterioration damage.
- 4. Unless adequate negative resistance is allocated in the oscillation circuit, start up time of oscillation may be increased, or no oscillation may occur.

How to check the negative resistance.



- (1) Connect the resistance (R) to the circuit in series with the crystal resonator.
- (2) Adjust R so that oscillation can start (or stop).
- (3) Measure R when oscillation just start (or stop) in above (2).
- (4) Get the negative resistance

$$-R = R + CI$$
 value.

(5) Recommended -R

$$|-R| > CI \times (5 \sim 10)$$

- 5. The shortest patterning line on board is recommendable.

 Too long line on board may cause of abnormal oscillation.
- 6. This device must be stored at the normal temperature and humidity conditions before mounting on a board.
- 7. Too much exciting shock or vibration may cause deterioration on damage.
 Depending on the condition such as a shock in assembly machinery, the products may be damaged.
 Please check your condition in advance to maintain shock level to be smallest.
- 8. Depending on the conditions, ultrasonic cleaning may cause resonant damage of the internal crystal resonator. Since we are unable to determine the conditions (type of cleaning unit, power, time, conditions inside the bath, etc.) to be used in your company, we cannot guarantee the safety of this unit when it is cleaned in an ultrasonic cleaner.
- 9. Please refer to packing specification regarding how to storage the products in the pack.

TAPING SPECIFICATION

テープ梱包基準書

1. APPLICATION 適用範囲

This document is applicable to FC-13A. 本基準書は、FC-13A のテーピング梱包について規定する。

2. CONTENTS 目次

Item No.	Item	Page
[1]	Taping specification テーピング仕様	2 to 3
[2]	Shipping carton 外装箱への収納	4
[3]	Marking 表示	
[4]	Quantity 収納数量	5
[5]	Storage environment 保管環境	
[6]	Handling リール取扱い	

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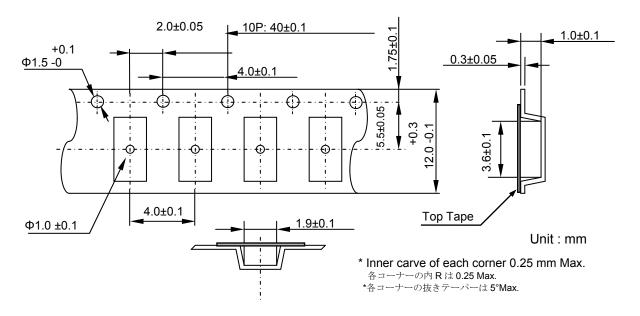
[1] Taping specification テーピング仕様

Subject to EIA-481, IEC 60286, JIS C0806.

「EIA-481」「IEC 60286」「JIS C0806」に準拠する。

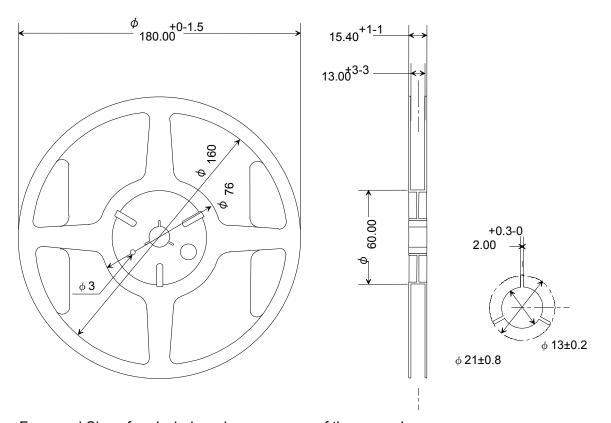
(1) Tape dimensions TE1204L

Material of the Carrier Tape キャリアテープ材質: PS (Electrically conductive) Material of the Top Tape トップテープ材質 : PET+PE



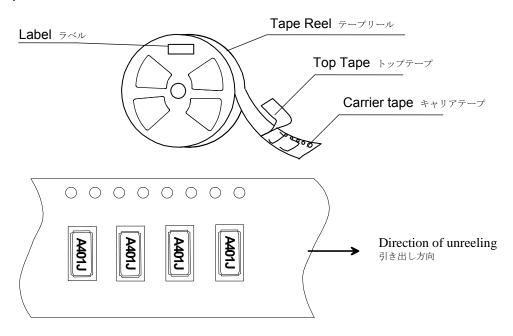
(2) Reel dimensions

Material of the Reel リール材質: PS

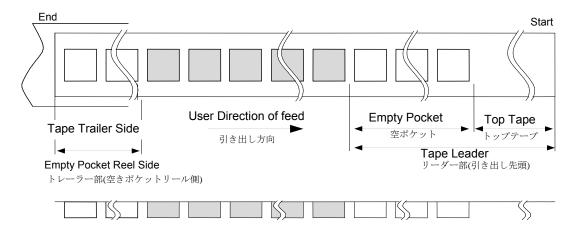


Form and Size of reel window shows are one of the example リールの窓の形状は代表例を掲載。

- (3) Packing 収納形態
 - (a) Tape & Reel デバイス収納方法



(b) Start & End Point 引き出し先頭側及びリール側の処理

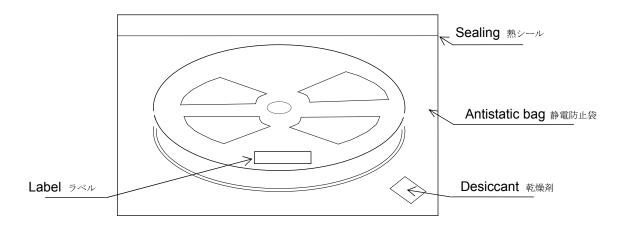


It	em	Empty Space 空きスペース	Note 備考		
Tape Leader	Top Tape	Min. 1 000 mm	Feeding in the Top tape, the tip is fixed with tape. トップテープ単独で繰り出し、先端はテーブにより固定。		
(引き出し先頭側)	Carrier Tape	Min. 160 mm	Winding method is a diagram of the above リールへの巻き取り方法は、上図の通り。		
Tape Trailer	Top Tape	Min. 0 mm			
(リール側)	Carrier Tape	Min. 160 mm	Tip is fixed to the reel. 先端はリールに固定。		

- (4) Peel force of the cover tape トップテープの剥離強度
 - (a) angle: cover tape during peel off and the direction of unreeling shall be 165° to 180°. 剥離角度:テープの接着面に対し165~180度とする。
 - (b) peel speed: 300 mm/min 剥離速度: 300 mm/min とする。

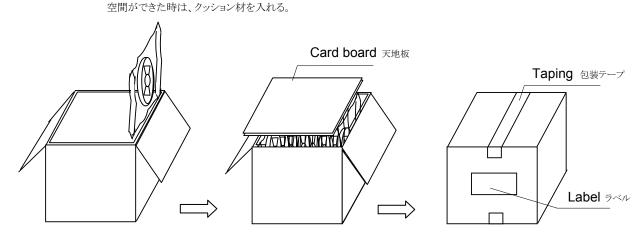
[2] Shipping Carton 外装箱への収納

a) Packing to antistatic bag 袋への収納



b) Packing to shipping carton 外装箱への収納

If there is space in the outer box, material is put in a shock absorbing together.



[3] Marking 表示

- (1) Reel marking リールへの表示
 - Reel marking shall consist of
 - 下記内容をリール表面に表示できるラベルを貼る。:
 - 1) Parts name 製品名称
 - 2) Quantity 製品数量
 - 3) Manufacturing Date or symbol 製品の製造年月又はこれを示す記号
 - 4) Manufacturer's Date or symbol 製品の製造業者又はその略号
 - 5) Others (if necessary) その他必要事項
- (2) Shipping carton marking 外装箱への表示
 - Shipping carton marking shall consist of: 下記内容を外装箱表面に表示できるラベルを貼る。:
 - 1) Parts name 製品名称
 - 2) Quantity 製品数量

[4] Quantity 収納数量

• 3 000 pcs./reel (Standard)

However it is not the limit, in case that the order quantity does not fill with 3000 pieces. Packing quantity is defined by 14th and 15th digit of product number.

但し、注文数量が $3\,000\,\mathrm{pcs}$ に満たない場合は、その限りではない。 収納数量は、製品型番の $14\,\mathrm{fn}$ 、 $15\,\mathrm{fn}$ による。

14th and 15th digit of product number. 製品型番の 14 桁、15 桁	Quantity
00	3 000 pcs
01	Vinyl Bag(Tape cut)
11	Any Quantity
12	250 pcs
13	500 pcs
14	1 000 pcs
15	2 000 pcs

[5] Storage environment 保管環境

(1) Before open the packing, we recommend to keep less than +30 °C and 85 %RH of Humidity, and to use it less than 6 months after delivery.

開梱前の製品は、温度 +30 °C、湿度 85 %RH 以下での保管をして下さい。 貴社納入後、袋未開封で 6 ヶ月以内の実装を推奨します。

(2) We recommend to open Package in immediately before use. After open Package, We recommend to keeps less than 6 month. No need dry air before soldering work if it is less than temperature +30 °C, 85 humidity %RH.

使用直前まで開梱せず、袋開封後は6ヶ月以内の実装を推奨します。 温度 +30 $^{\circ}$ C、湿度 85 %RH 以下では、はんだ付け作業前に乾燥不要です。

(3) Not to storage with some erosive chemicals.

化学薬品類との同居を避ける。

(4) Nothing is allowed to put on the reel or carton to prevent mechanical damage 外装箱がゆがまないようまた、外圧がかからないように保管して下さい。

[6] Handling リール取扱い

To handle with care to prevent the damage of tape, reel and products.

リールの取扱いについては、中のテープ・製品を変形させないようにして下さい。

PROCESS QUALITY CONTROL

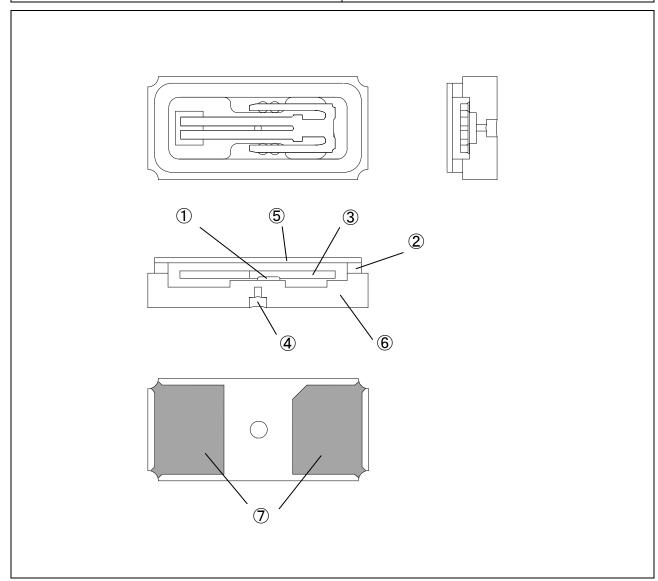
FC-13A

No. C-0901-02-AME

2015.03.09 FC13A_Q_0001

	Manufacturing process chart	No.	Section In Charge	Standard	Inspection Control Item	Inspection Methods	Instruments	Record
Base	Crystal In-coming	1	Inspection Section	Purchasing Specification	Appearance	Sampling	Microscope	Incoming Inspection
\wedge	In-coming inspection			Incoming Inspection Standard	Dimension	Sampling	Tool Microscope	Data sheet
(1-2)	Ag paste	2	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	2 Tuning fork setting $\sqrt{-3}$	3	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	Mounting	4	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	3 Mounting	5	Production Section	Manufacturing Instruction	_	_	_	_
	4 Ag paste cure	6	Production Section	Manufacturing Instruction	_	_	_	_
	5	7	Production Section	Manufacturing Instruction	Frequency	100% Inspection	Frequency adjustment Machine	Data sheet
	US cleaning	8	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	6 Annealing Lid	9	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Spot welding machine	Process data sheet
	6 Annealing Lid	10	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	7 Frequency adjustment 4-4	11	Production Section	Manufacturing Instruction	_	_	_	_
	Q Outer appearance	12	Production Section	Manufacturing Instruction	_	_		_
	inspection	13	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	9	14	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
Ball	Spot welding	15	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
1-5/		16	Production Section	Manufacturing Instruction	Frequency	100% Inspection	Charcteristic	Process data sheet
	11 Ball setting				Crystal Impedance	100% Inspection	Inspection machine	
·	11 Ball setting				Appearance	100% Inspection	Microscope	
	(12) Hermetic sealing	17	Production Section	Manufacturing Instruction	Appearance	100% Inspection	Microscope	Process data sheet
	Outer appearance inspection	18	Production Section	Specification	Electrical Characteristic	Sampling	Measurmente equipment	Outgoing Inspection data sheet
				Outgoing Inspection Standard	Appearance	Sampling	Microscope	
	(14) Marking				Dimension	Sampling	Tool Microscope	
	Outer appearance	19	Production Section	Packing Instruction	Customer	_	_	Shipping List
	inspection			Daily Shipping List	Туре	_	_	
	Electrical characteristic inspection & taping				Quantity	_		
	Outer appearance inspection							
	0 Outgoing inspection							
	19 Packing Shipping							

Structure Diagram 構造図		Rev.01
Model 型式	FC-13A	
Document No. 管理No.	FC135_D_0001	



No.	Name of Part 部品名	
1	Crystal adhesive 水晶接着	
2	Sealing 封止材(シールリング)	
3	Crystal chip 水晶片	
4	Sealing 封止材	
5	Lid リッド	
6	Package パッケージ	
7	Terminal 端子	

RELIABILITY TEST DATA

Product Name: FC-13A

The Company evaluation condition

We evaluate environmental and mechanical characteristics by the following test condition . No. F-020C-C-0901-01-001E

VALUE *1 *2 TEST FAIL

No.	ITEM	TEST CONDITIONS	VALUE *1 *2 Δ f/f [1 × 10 ⁻⁶]	TEST Qty [n]	FAIL Qty [n]
1	Shock resistance	Free drop from 1 000 mm height on a hard wooden board for 3 times (Board is thickness more than 30 mm)	*3 ± 10	22	0
2	Vibration resistance	10 Hz to 55 Hz amplitude 0.75 mm 55 Hz to 500 Hz acceleration 98 m/s2 10 Hz →500 Hz →10 Hz 15 min./cycle 6 h (2 hours . 3 directions)	*3 ± 5	22	0
3	Soldering heat resistance	IPC/JEDEC J-STD-020C Reflow (3 times)	± 5	22	0
4	High temperature storage	+125°C × 1 000 h	*3 ± 20	22	0
5	Low temperature storage	-55 ℃ × 1 000 h	*3 ± 15	22	0
6	Temperature humidity storage	+85 °C × 85 %RH × 1 000 h	*3 ± 10	22	0
7	High temperature bias	+125°C × 1 000 h (Bias , Drive level ; 0.5 μ W)	*3 ± 20	22	0
8	Low temperature bias	-40 °C × 1 000 h (Bias , Drive level ; 0.5 μ W)	*3 ± 15	22	0
9	Temperature humidity storage bias	+ 85°C × 85 %RH × 1 000 h (Bias , Drive level ; 0.5 μW)	*3 ± 15	22	0
10	Temperature cycle	-40 $^{\circ}$ C \Leftrightarrow +125 $^{\circ}$ C 30 min at each temp. 1 000 cycles	*3 ± 15	22	0
11	Sealing	For He leak detector	*3 1× 10 ⁻⁸ hPa·1/s Max.	11	0
12	Shear	20 N press for 10 s ± 1 Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
13	Pull - off	20 N press for 10 s ± 1 Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
14	Substrate bending	Bend width reaches 4 mm and hold for $20 \text{ s} \pm 1 \text{ s} \times 1 \text{ time}$ Ref. IEC 60068-2-21	No peeling - off at a solder part	11	0
15	Solderability	Dip termination into solder bath at $+235 ^{\circ}\text{C} \pm 10 ^{\circ}\text{C}$ for 3 s (Using Rosin Flux)	Termination must be 95 % covered with fresh solder	11	0

Notes

^{*1} Each test shall be done independently.

^{*2} Measuring 2 h to 24 h later leaving in room temperature after each test. Drive level: $0.5 \mu w$

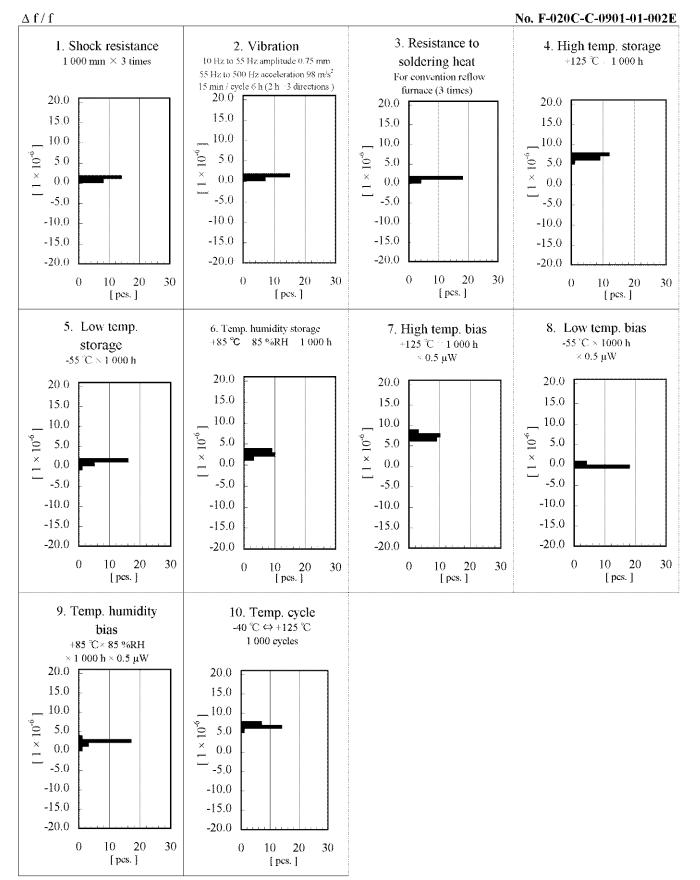
^{*3} Pre conditionings

^{1.} ± 125 °C × 24 h to ± 85 °C × 85 % × 168 h \pm 1 h \rightarrow reflow 3 times

^{2.} Initial value shall be after 24 h at room temperature.

Shift of series resistance at before and after the test should be less than $\pm 30 \text{ k}\Omega$.

Product Name: FC-13A



Qualification Data

Product Name: FC-13A

